

**INFORMATION DISCLOSURE CITATION**  
*(Use several sheets if necessary)*

 ATTY DOCKET NO.  
 FIS920040098US1

 APPLICATION NO.  
 10/711,076

Bernier et al.

 FILING  
 8/20/04

 GROUP ART  
 Unknown

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**U.S. PATENT APPLICATION PUBLICATIONS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
DF	2001127108	11/05/01	Japan				

**OTHER DOCUMENTS** *(Including Author, Title, Date, Pertinent Pages, Etc.)*


EXAMINER

*Da Shen*

DATE CONSIDERED

9/15/05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	<b>COMPRESSIBLE FILMS SURROUNDING SOLDER CONNECTORS</b>
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Application Number :

Confirmation Number:

First Named Applicant: William Bernier

Attorney Docket Number: FIS920040098US1

Art Unit:

Examiner:

Search string: ( 6483191 or 5274913 or 6281452 or 6573122 or 6100114 or 20030230792 ).pn

## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DP	1	6483191	2002-11-19	Umezaki			
	2	5274913	1994-01-04	Grebe et al			
	3	6281452	2001-08-28	Prasad et al			
	4	6573122	2003-06-03	Standing			
DP	5	6100114	2000-08-08	Milkovich et al			

## US Published Applications

**Note: Applicant is not required to submit a paper copy of cited US Published Applications**

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
DP	1	20030230792	2003-12-18	Wu et al			

## Signature

Examiner Name	Date
	9/5/05